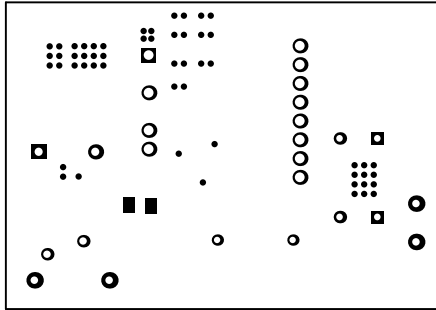
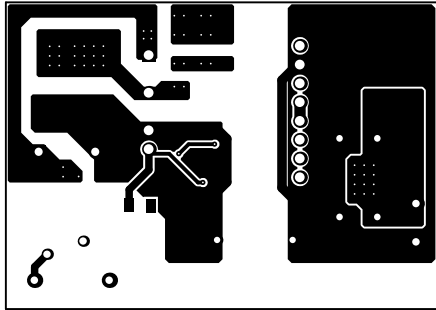


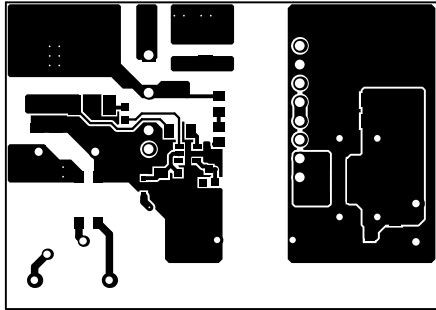
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10276	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/24/2014 2:51:46 PM	TEXAS INSTRUMENTS	



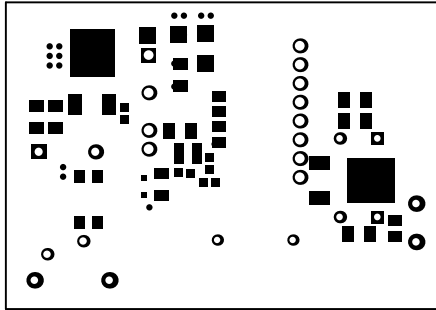
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/24/2014 2:51:46 PM	TEXAS INSTRUMENTS	



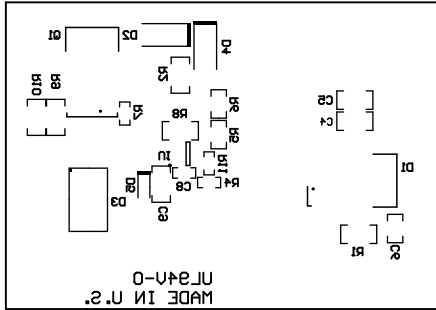
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10276	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/24/2014 2:51:47 PM	TEXAS INSTRUMENTS	



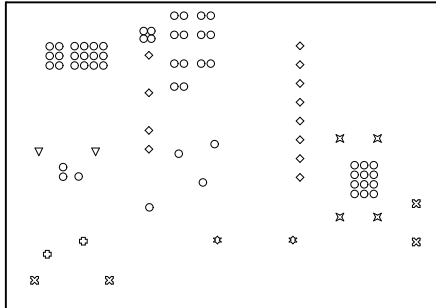
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10276	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/24/2014 2:51:47 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10276	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/24/2014 2:51:48 PM	TEXAS INSTRUMENTS	



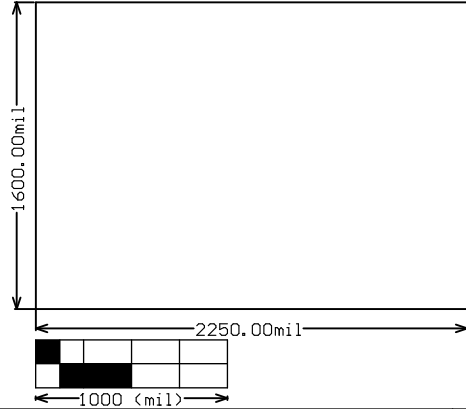
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10276	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/24/2014 2:51:49 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	55	0.254mm (10mil)	PTH	Round
*	2	0.85mm (33.465mil)	PTH	Round
×	4	0.9mm (35.433mil)	PTH	Round
⊕	2	1mm (39.37mil)	PTH	Round
⊗	4	1.016mm (40mil)	PTH	Round
▽	2	1.1mm (43.307mil)	PTH	Round
◇	12	1.32mm (51.968mil)	PTH	Round
	81 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10276	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/24/2014 2:51:49 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10276	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/24/2014 2:51:50 PM	TEXAS INSTRUMENTS	

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